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## U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date
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## Foreign Patent or Published Foreign Patent Application

Examiner Initial		Document No.	Publication Date	Country or Patent Office	Class	Sub- Class	Translation Yes No
/BC/	20.	WO 03/052794 A2	26.06.2003	PCT			
/BC/	21.	WO 03/005429 A1	16.01.2003	PCT			

## Other Documents

Examiner Initial	Author, Title, Place (e.g. Journal) of Publication, Date
/BC/	U.S. Office Action mailed November 30, 2006, from U.S Application No. 10/927,777 [Atty Dkt No. NOVLP106/NVLS-2930].

Examiner	/Bret Chen/	Date Considered	02/04/2008
Examiner:	Initial citation considered.	Draw line through citation	if not in conformance and

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form 1449 (Modified)	Atty Docket No.	NOVLP094/NVLS-2919
	Application No.:	10/789,103
Information Disclosure	Applicant	Wu et al.
Statement By Applicant	Filing Date	February 27, 2004
	Group	1762
(Use Several Sheets if Necessary)		Page 2 of 2

I	23.	U.S. Office Action mailed March 28, 2007, from U.S Application No. 10/820,525
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	24.	U.S. Notice of Allowance and Fee Due mailed December 19, 2006, from U.S.
	2	Application No. 10/800,409. [NOVLP098/NVLS-2907]
	25.	U.S. Office Action mailed April 9, 2007, from U.S Application No. 10/800,409 [Atty
	25.	Dkt No. NOVLP098/NVLS-2907].
	26.	Niu et al., "Methods for Improving the Cracking Resistance of Low-K Dielectric
1	20.	Materials," Novellus Systems, Inc., Appl. No. 11/376,510, filed March 14,2006,
		pages 1-28. [NOVLP099D1/NVLS-2896D1]
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	20.	No. 10/927,777. [NOVLP106/NVLS-2930]
	29.	Allowed Claims from U.S. Application No. 10/927,777. [NOVLP106/NVLS-2930]
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1	32.	Wu et al., "PECVD Methods for Producing Ultra Low-K Dielectric Films Using UV
	02.	Treatment," Novellus Systems, Inc., Appl. No.11/608,056, filed December 7, 2006,
		pages 1-34. [NOVLP196/NVLS-3238]
	33.	Wu et al., "Methods for Improving Performance of ODC Films with Dielectric
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		[Atty Dkt No. NOVLP091/NVLS-2889].
	38.	U.S. Office Action mailed October 29, 2007, from U.S Application No. 11/764,750
/BC/		[Atty Dkt No. NOVLP106D1.

Examiner	/Bret Chen/	Date Considered	02/04/2008